

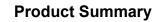
-20V P-Channel MOSFET

General Features

- R_{DS(ON)} <21mΩ @ V_{GS} = -4.5V
 R_{DS(ON)} <28mΩ @ V_{GS} = -2.5V
- High Power and Current Handing Capability
- Lead Free Product is Acquired
- Surface Mount Package

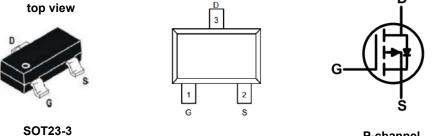
Applications

- PWM Applications
- Load Switch
- Power Management





VDS	-20	V
RDS(on),max.@ VGS=4.5 V	21	mΩ
ID	-9	А



P-channel

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
Vdss	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		±12	V
1-	Continuous Drain Current	T _C = 25℃	-9	•
ID		T _C = 100°C	-5	А
I _{DM}	Pulsed Drain Current note1		-15	А
PD	Power Dissipation	Tc = 25℃	1.8	W
R _{eJC}	Thermal Resistance, Junction to Ambient		6.9	°C/W
TJ, T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C



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Electrical Characteristics (Tc=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Charac	teristic			1	1		
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250µA	-20	-	-	V	
IDSS	Zero Gate Voltage Drain Current	V_{DS} = -20V, V_{GS} = 0V,	-	-	-1	μA	
Igss	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA	
On Charac	teristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250µA	-0.4	-0.7	-1.0	V	
P	Static Drain-Source on-Resistance	V _{GS} =-4.5V, I _D =-4.A	-	16	21	mΩ	
$R_{DS(on)}$	note2	V _{GS} =-2.5V, I _D =-3.A	-	20	28		
g fs	Forward Transconductance	V _{DS} =-5V, I _D = -6.7A	20	-	-	S	
Dynamic (Characteristics						
Ciss	Input Capacitance		-	1200	-	pF	
Coss	Output Capacitance	$V_{DS} = -10V, V_{GS} = 0V,$	-	230	-	pF	
Crss	Reverse Transfer Capacitance	- f = 1.0MHz	-	90	-	pF	
Qg	Total Gate Charge	$y_{1} = 40y_{1} = 0.0$	_	15	48	nC	
Qgs	Gate-Source Charge	V _{DS} = -16V, I _D = -9A, V _{GS} = -4.5V	-	4	-	nC	
Q_{gd}	Gate-Drain("Miller") Charge	- VGS = -4.5V	-	6	-	nC	
Switching	Characteristics						
t _{d(on)}	Turn-on Delay Time		-	11	-	ns	
tr	Turn-on Rise Time	V _{DD} = -10V, I _D = -1A,	-	18	-	ns	
t _{d(off)}	Turn-off Delay Time	R _{GEN} =10Ω,V _{GS} =-4.5V	-	30	-	ns	
tr	Turn-off Fall Time	-	-	10	-	ns	
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings					
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	-1	А	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	-10	А	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -8A	-	-	-1.2	V	

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



Typical Performance Characteristics

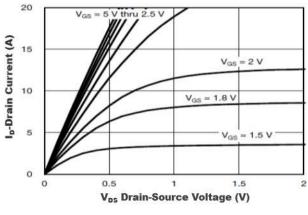


Figure 1. Output Characteristics

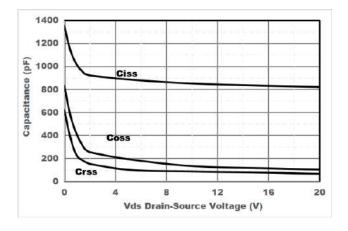


Figure 3. Capacitance Characteristics

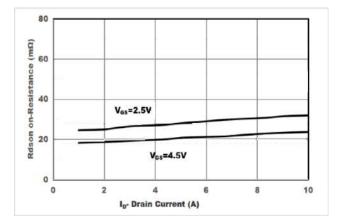


Figure5. Drain-Source on Resistance

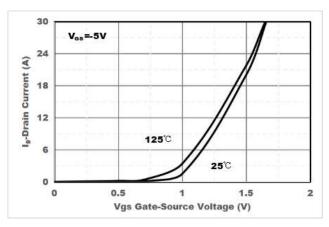


Figure 2. Transfer Characteristics

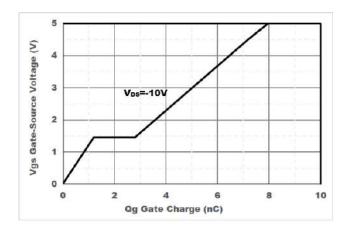


Figure4. Gate Charge

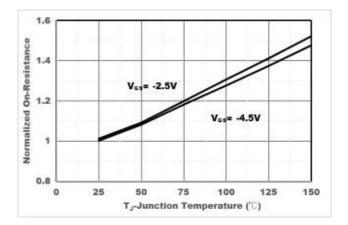


Figure6. Drain-Source on Resistance



ASDM20P09ZB

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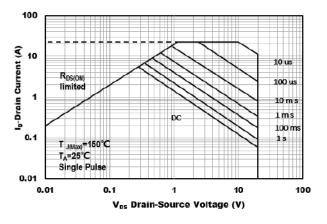


Figure7. Safe Operation Area

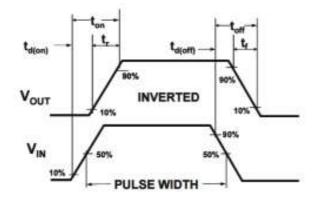
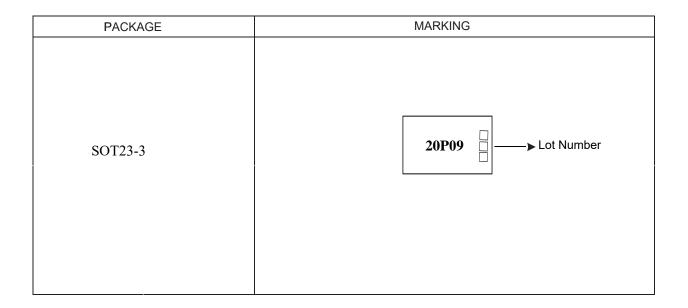


Figure8. Switching wave



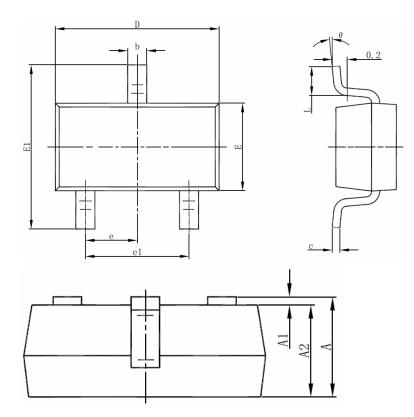
Ordering and Marking Information

Ordering Device No	Marking	Package	Packing	Quantity
ASDM20P09ZB-R	20P09	SOT23-3	Tape&Reel	3000/Reel





SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
с	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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